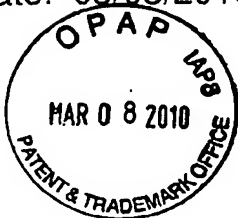


Receipt date: 03/08/2010



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03/17/2010

RESPONSE UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE

IN THE U.S. PATENT AND TRADEMARK OFFICE

March 4, 2010

*Enter RCB  
04/05/10  
AS*

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING SOLUTION

Serial No.: 10/576 231 Group: 1792

Confirmation No.: 7188

Filed: April 14, 2006 Examiner: Bareford

International Application No.: PCT/JP2004/011327

International Filing Date: July 30, 2004

Atty. Docket No.: 4700.P0327US

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AFTER FINAL REJECTION**

Sir:

In response to the Office Action dated January 5, 2010,  
please amend the above-identified application as follows:

(Please see following pages.)

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being  
deposited with the United States Postal Service with  
sufficient postage as first class mail in an envelope  
addressed to: Commissioner for Patents, P.O. Box 1450,  
Alexandria, VA 22313-1450, on March 4, 2010.

  
Terryence F. Chapman